

6-Channel Buffer and Driver with Open-Drain Outputs

Description

The FLG6G07 6-channel buffer and driver is designed for 1.65V to 5.5V V_{CC} operation.

The FLG6G07 device is open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The device is fully specified for partial-power-down applications using loff. The loff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The FLG6G07 is available in Green SOP14, TSSOP14 packages. It operates over an ambient temperature range of -40°C to 125°C.

Features

- Operating Voltage Range: 1.65V to 5.5V
- Low Power Consumption:1µA (Max)
- Operating Temperature Range: -40°C to +125°C
- Inputs and Open-Drain Outputs accept
 Voltage to 5.5V
- High Output Drive: ±24mA at V_{CC}=3.0V
- Packages: SOP14, TSSOP14

Applications

- Blu-ray Players and Home Theaters
- Desktops or Notebook PCs
- Digital Video Cameras (DVC)
- Mobile Phones

1

- Personal Navigation Device (GPS)
- Portable Media Player



Order information (1)

Mode	Package	Specified Temperature range	Ordering Number	Packing Option	
EL C(C07	SOP14	-40°C to +125°C	FLG6G07YSOP14G/TR	Tape and Reel,4000	
FLG6G07	TSSOP14	-40°C to +125°C	FLG6G07YTSSOP14G/TR	Tape and Reel,4000	

Note:

(1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document.

Functional Block Diagram



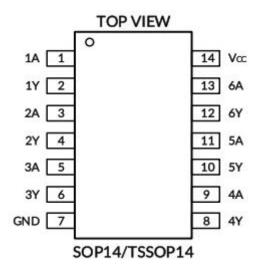
Function Table

INPUT	OUTPUT
A	Y
L	L
Н	Z

Note:

H=High Voltage Level, L=Low Voltage Level, Z=High-impedance OFF-state

Pin Configuration





Pin Description

Name	Pin SOP14/TSSOP14	I/O (1)	Description
1A	1	I	Input 1
1Y	2	О	Open-drain output 1
2A	3	I	Input 2
2Y	4	О	Open-drain output 2
3A	5	I	Input 3
3Y	6	О	Open-drain output 3
GND	7	P	Ground
4Y	8	О	Open-drain output 4
4A	9	I	Input 4
5Y	10	О	Open-drain output 5
5A	11	I	Input 5
6Y	12	О	Open-drain output 6
6A	13	I	Input 6
V_{CC}	14	P	Power pin

Note:

I=input, O=output, P=Power.

Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)(2)

			Min	Max	Unit
V_{CC}	Supply voltage range		-0.5	6.5	V
V_{I}	Input voltage range (2)		-0.5	6.5	V
Vo	Output Voltage range (2)		-0.5	6.5	V
I _{IK}	Input clamp current V _I <0			-50	mA
I _{OK}	Output clamp current V_{O} <0			-50	mA
Io	Io Continuous output current			±50	mA
	Continuous current through Vcc or GND			±100	mA
		SOP14		105	
$\theta_{ m JA}$	Package thermal impedance (3)	TSSOP14		90	°C/W
TJ	T _J Junction temperature ⁽⁴⁾		-65	150	°C
T_{stg}	Storage temperature		-65	150	°C

Note:

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated



under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD-51.
- (4) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

		Value	Unit
	Human-body model (HBM)	± 7000	V
V Electrostatic discharge	Charged device model (CDM)	±1500	V
V _(ESD) Electrostatic discharge	Machine model (MM))	±400	V



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Recommanded Operating Range

over recommended operating free-air temperature range (TYP values are at $T_A = +25$ °C, unless otherwise noted.) (1)

Parameter	Symbol	Test Conditions	Min	Max	Unit
	3 7	Operating	1.65	5.5	***
Supply voltage	V_{CC}	Data retention only	1.5		V
		V _{CC} =1.65V to 1.95V	$0.65 \mathrm{xV}_{\mathrm{CC}}$		
		V _{CC} =2.3V to 2.7V	1.7		
High-level input voltage	V_{IH}	V_{CC} =3V to 3.6V	2.2		v
		V _{CC} =4.5V to 5.5V	$0.7 \mathrm{xV}_{\mathrm{CC}}$		
		V _{CC} =1.65V to 1.95V		$0.15 \text{xV}_{\text{CC}}$	
		V _{CC} =2.3V to 2.7V		0.3	
Low-level input voltage	V_{IL}	$V_{CC}=3V$ to 3.6V		0.4	v
		V _{CC} =4.5V to 5.5V		$0.15 \mathrm{xV}_{\mathrm{CC}}$	
Input voltage	$V_{\rm I}$		0	5.5	V
Output voltage	Vo		0	5.5	V

FLG6G07



		V_{CC} =1.8V± 0.15V,2.5V ± 0.2V		20	
Input transition rise or fall	tr, tf	$V_{CC}=3.3V\pm0.3V$		10	ns/V
input transition rise of fair	и, и	$V_{CC}=5V\pm0.5V$		5	IIS/ V
Operating temperature	T_A		-40	+125	°C

Note: (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

Electrical Characteristics

DC Characteristics

over recommended operating free-air temperature range (TYP values are at $T_A = +25$ °C, unless otherwise noted.) (1)

Parameter		Test Conditions	$V_{\rm CC}$	Temp	Min ⁽²⁾	Typ ⁽³⁾	Max ⁽²⁾	Unit
		$I_{OL} = 100 \mu A$	1.65V to 5.5V				0.1	
		$I_{OL} = 4mA$	1.65V				0.45	
	1 7	$I_{OL} = 8mA$	2.3V	F 11			0.3	
	$ m V_{OL}$	$I_{OL} = 16mA$	277	Full			0.4	
		$I_{OL} = 24mA$	3V				0.55	V
		$I_{OL} = 32mA$	4.5V				0.55	
11	A D: 4	W CON CND	011. 5.51	+25°C		±0.1	±1	
II	A or B inputs	V_I =5.5V or GND	0V to 5.5V	Full			±5	μA
	1 00	X	0	+25°C		±0.1	±1	
	Ioff	$V_{\rm I}$ or $V_{\rm O}$ =5.5 V		Full			±10	μA
I_{CC}		W CON CND I O	1 (5) 1 (5)	+25°C		0.1	1	
		V_I =5.5V or GND, I_O =0	1.65V to 5.5V	Full			10	μΑ
ΔI_{CC}		One input at V_{CC} -0.6V, Other inputs at V_{CC} or GND	3V to 5.5V	Full			500	μΑ

Note:

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



AC Characteristics

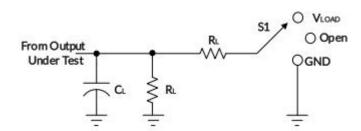
over recommended operating free-air temperature range (TYP values are at $T_A = +25$ °C, unless otherwise noted.) (1)

Parameter	Symbol	Test Conditions		Temp	Min ⁽²⁾	Typ ⁽³⁾	Max ⁽²⁾	Unit
		V _{CC} =1.8V±0.15V	$C_L=30pF, R_L=1k\Omega$	Full		6.4		
		V _{CC} =2.5V±0.2V	$C_L=30pF, R_L=500\Omega$	Full		4.5		
Propagation Delay	$t_{ m pd}$	V _{CC} =3.3V±0.3V	$C_L=50pF, R_L=500\Omega$	Full		4.2		ns
		V _{CC} =5V±0.5V	$C_L=50pF, R_L=500\Omega$	Full		3.7		
Input Capacitance	Ci	V _{CC} =3.3V	V _I =V _{CC} or GND	+25°C		4		pF
		V _{CC} =1.8V				3		
D Dii		V _{CC} =2.5V				3		
Power Dissipation Capacitance	C_{pd}	V _{CC} =3.3V	f=10MHz	+25°C		4		pF
Сараспапсе		V _{CC} =5V				6		

Note:

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.
- (2) This parameter is ensured by design and/or characterization and is not tested in production.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

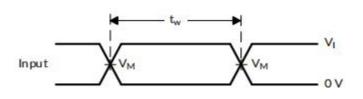
Parameter Measurement Information

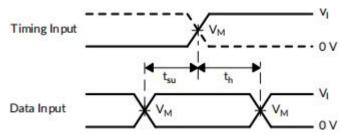


Test	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	$ m V_{LOAD}$
t _{PHZ} /t _{PZH}	GND

V	INPUTS		V	V	C	D	N/
V_{CC}	VI	tr/tf	V_{M}	V_{LOAD}	C_{L}	R_{L}	V_{Δ}
1.8V±0.15V	$V_{\rm CC}$	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	1kΩ	0.15V
2.5V±0.2V	V_{CC}	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	500Ω	0.15V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	$V_{\rm CC}$	≤2.5ns	V _{CC} /2	2 x V _{CC}	50pF	500Ω	0.3V

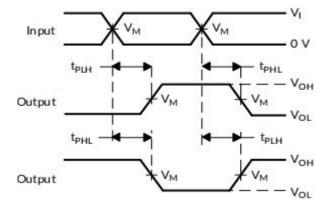


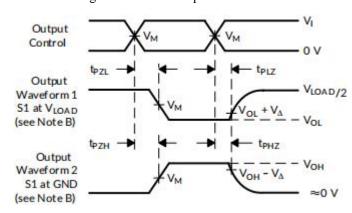




Voltage Waveforms Pulse Duration

Voltage Waveforms Setup And Hold Times





Voltage Waveforms Propagation Delay Times Invertion And Noninverting Outputs

Voltage Waveforms Enable And Disable Times Low-And High-Level Enabling

Notes:

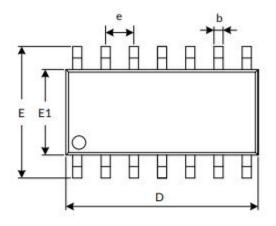
- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50\Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

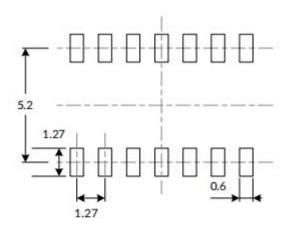
Figure 1. Load Circuit and Voltage Waveforms



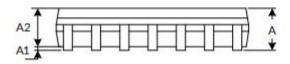
Package Outline Dimensions(All dimensions in mm.)

Package Type: SOP14 (3)





RECOMMENDED LAND PATTERN (Unit: mm)





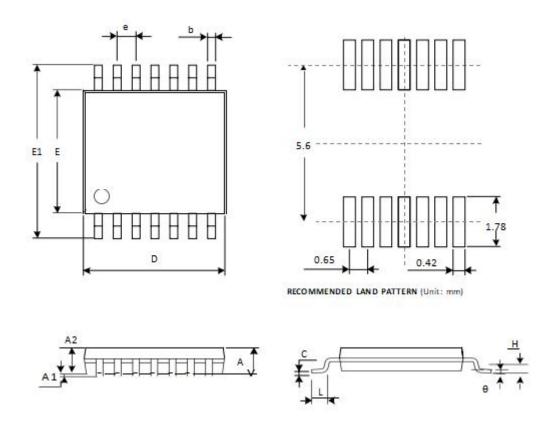
C11	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A ⁽¹⁾	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.310	0.510	0.012	0.020	
c	0.100	0.250	0.004	0.010	
D ⁽¹⁾	8.450	8.850	0.333	0.348	
e	1.270(H	BSC) (2)	0.050(BSC) (2)		
Е	5.800	6.200	0.228	0.244	
E1 ⁽¹⁾	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	

Note:

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 3. This drawing is subject to change without notice.



Package Type: TSSOP14 (3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D (1)	4.860	5.100	0.191	0.201
E (1)	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650(BSC) ⁽²⁾		0.026(BSC) (2)	
L	0.500	0.700	0.020	0.028
Н	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°

Note:

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 3. This drawing is subject to change without notice.



Important Notice And Disclaimer

- We reserves the right to change the instruction manual without prior notice.
- Any semiconductor product has a certain possibility of failure or malfunction under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design and overall manufacturing to avoid potential failure risks that may cause personal injury or property damage.
- The improvement of product quality is endless, our company will be dedicated to provide customers with better products.